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U.S. PATENT APPLICATION

for

**SHALLOW TRENCH ISOLATION FOR STRAINED SILICON
PROCESSES**

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CROSS-REFERENCE TO RELATED PATENT APPLICATIONS

FIELD OF THE INVENTION

[0001] The present invention is related to integrated circuit (IC) devices and to processes of making IC devices. More particularly, the present invention relates to a method of forming trench isolation liners for use in strained silicon metal oxide semiconductor (SMOS) or other ICs.

BACKGROUND OF THE INVENTION

[0002] Integrated circuits (ICs) include a multitude of transistors formed on a semiconductor substrate. Various methods of forming transistors on a semiconductor substrate are known in the art. Generally, transistors are isolated from each other by insulating or isolation structures.

[0003] One process for forming insulating structures and defining source and drain regions is a shallow trench isolation (STI) process. A conventional STI process typically includes the following simplified steps. First, a silicon nitride layer is thermally grown or deposited onto the silicon substrate. Next, using a lithography and etch process, the silicon nitride layer is selectively removed to produce a pattern where transistor source/drain areas are to be located. After patterning the source/drain areas, the substrate is etched to form trenches. After the trenches are formed, a liner is thermally grown on the exposed surfaces of the trench. The liner is typically an oxide material (e.g., SiO₂) formed at a very high temperature in a hydrochloric (HCl) acid

ambient. An insulative material, such as, silicon dioxide (SiO_2), is blanket deposited over the nitride layer and the liner within the trench. The insulative material is polished to create a planar surface. The nitride layer is subsequently removed to leave the oxide structures within the trenches.

[0004] Shallow trench isolation (STI) structures are utilized in strained silicon (SMOS) processes to separate NMOS (N-channel) and PMOS (P-channel) transistors. SMOS processes are utilized to form strained layers that increase transistor (MOSFET) performance by increasing the carrier mobility of silicon. Increasing carrier mobility reduces resistance and power consumption and increases drive current, frequency response and operating speed. Strained silicon is typically formed by growing a layer of silicon on a silicon germanium substrate or layer.

[0005] The silicon germanium lattice associated with the silicon germanium substrate is generally more widely spaced than a pure silicon lattice, with spacing becoming wider with a higher percentage of germanium. Because the silicon lattice aligns with the larger silicon germanium lattice, a tensile strain is created in the silicon layer. The silicon atoms are essentially pulled apart from one another.

[0006] Relaxed silicon has a conductive band that contains six equal valence bands. The application of tensile strain to the silicon causes four of the valence bands to increase in energy and two of the valence bands to decrease in energy. As a result of quantum effects, electrons effectively weigh 30 percent less when passing through the lower energy bands. Thus, the lower energy bands offer less resistance to electron flow. In addition, electrons meet with less vibrational energy

from the nucleus of the silicon atom, which causes them to scatter at a rate of 500 to 1000 times less than in relaxed silicon. As a result, carrier mobility is dramatically increased in strained silicon compared to relaxed silicon, providing an increase in mobility of 80% or more for electrons and 20% or more for holes. The increase in mobility has been found to persist for current fields up to 1.5 megavolts/centimeter. These factors are believed to enable a device speed increase of 35% without further reduction of device size, or a 25% reduction in power consumption without a reduction in performance.

[0007] Complementary metal oxide semiconductor (CMOS) IC's utilize NMOS and PMOS transistors. NMOS transistors are generally provided in P-type wells or on a P-type substrate. P-channel transistors are generally provided in N-type wells disposed in a P-type substrate. Generally, STI structures separate transistors in N-type wells from transistors in P-type wells.

[0008] The STI liner (typically an oxide liner) can create stress in the channel associated with N-type and P-type transistor. However, if the same liner (the same material and/or the same thickness) is utilized for both N-type or P-type transistors, the stress created by the STI liner is different for the N-type transistors than it is for the P-type transistors. For example, an oxide liner may be more beneficial for stress in one type of N or P-doped region than in another type of N or P-region of a CMOS IC. Differentiated stress between N and P-type regions affects the operational characteristics of the N and P-type transistors.

[0009] Thus, there is a need for an STI liner fabrication scheme which creates similar stress in P-type and N-type regions. Further still, there is a need for a process of forming high quality oxides for N and

PMOS regions with superior stress. Further still, there is a need for a differentiated SMOS trench liner formation process for CMOS processes. Further still, there is a need for an STI process that utilizes different materials or thickness of liners according to NMOS and PMOS transistor locations. Yet further, there is a need for an IC with differentiated liners for isolation structures. Yet further still, there is a need for a differentiated STI liner process that equalizes stress in N and P-type channels.

SUMMARY OF THE INVENTION

[0010] The present invention relates to a method of manufacturing an integrated circuit having trench isolation regions in a substrate. The method includes forming a mask layer above the substrate, selectively etching the mask layer to form apertures associated with the locations of the trench isolation regions, and forming trenches in the substrate at the locations. The method also includes forming first type liners on first side walls of the trenches associated with the first type regions of the substrate, and forming second type liners on second side walls of the trenches associated with second type regions.

[0011] Another exemplary embodiment relates to a method of forming trench isolation liners in a CMOS IC. The method includes forming a trench in a layer above a substrate or in the substrate, forming a first liner for a first side wall in the trench, and forming a second liner for a second side wall of the trench. The trench separates a first doped region from a second doped region. The first side wall is associated with the first doped region and the second side wall is associated with the second doped region.

[0012] Still another exemplary embodiment relates to an integrated circuit. The integrated circuit includes a first doped region of a substrate and a second doped region of a substrate, a first liner, and a second liner. The first liner is disposed on a first side wall of a trench between the first doped region and the second doped region. The second liner is disposed on a second side wall of the trench.

BRIEF DESCRIPTION OF THE DRAWINGS

[0013] Exemplary embodiments will become more fully understood from the following detailed description, taken in conjunction with the accompanying drawings, wherein like reference numerals refer to like parts, and wherein:

[0014] FIGURE 1 is a top view of a portion of an integrated circuit including a trench structure in accordance with an exemplary embodiment;

[0015] FIGURE 2 is a cross-sectional view of the portion illustrated in FIGURE 1, taken about line 2-2 showing the trench structure;

[0016] FIGURE 3 is an enlarged cross-sectional view associated with encircled section 3 illustrated in FIGURE 2, in accordance with another exemplary embodiment;

[0017] FIGURE 4 is a general flow diagram of a process for forming the portion of the integrated circuit illustrated in FIGURE 3 in accordance with yet another exemplary embodiment;

[0018] FIGURE 5 is a cross-sectional view of the portion illustrated in FIGURE 3, showing a trench etching step;

[0019] FIGURE 6 is a cross-sectional view of the portion illustrated in FIGURE 5, showing a first liner oxidation step;

[0020] FIGURE 7 is a cross-sectional view of the portion shown in FIGURE 3, showing a second liner oxidation step;

[0021] FIGURE 8 is a cross-sectional view of the portion illustrated in FIGURE 3, showing a trench filling step;

[0022] FIGURE 9 is a cross-sectional view corresponding to another embodiment similar to the cross-sectional view illustrated in FIGURE 3;

[0023] FIGURE 10 is a cross-sectional view of the portion illustrated in FIGURE 9, showing a trench etching step;

[0024] FIGURE 11 is a cross-sectional view of the portion illustrated in FIGURE 9, showing a first liner oxidation step;

[0025] FIGURE 12 is a cross-sectional view of the portion illustrated in FIGURE 9, showing a second liner oxidation step; and

[0026] FIGURE 13 is a cross-sectional view of the portion illustrated in FIGURE 3, showing a trench filling step.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0027] FIGURES 1 through 8 illustrate a method of manufacturing an integrated circuit (IC) in accordance with an exemplary embodiment on a bulk substrate. FIGURES 1, 2, 4 and 9-13 illustrate a method of manufacturing an IC in accordance with another exemplary embodiment on a semiconductor-on insulation (SOI) substrate. The methods illustrated in FIGURES 1 through 13 reduce the stress differentials associated with liners disposed on trenches separating differently doped regions. The methods can be used in a shallow trench isolation (STI) process or any process requiring a liner oxide where stress or strains are of concern, such as, in an SMOS process. Advantageously, the liner oxides can be formed in two different process steps and yet provide a high quality oxide with good compatibility.

[0028] Referring to FIGURES 1 and 2, a portion 10 of an

integrated circuit (IC) is illustrated. Portion **10** is subjected to process **100** (FIGURE 4) to form a trench isolation region, such as a shallow trench isolation (STI) structure **16**. Portion **10** includes a substrate such as bulk substrate **20**. Substrate **20** can include or be a germanium-containing layer or substrate.

[0029] Substrate **20** can be provided as an SOI substrate (a structure with a substrate below a buried oxide layer that is below a strained layer). The embodiment described with reference to FIGURES 9-13 shows a substrate **220** in accordance with an SOI structure. Substrate **20** can be any of a variety of IC materials. In one embodiment, substrate **20** is a semiconductor substrate such as a strained silicon substrate.

[0030] Portion **10** can be any type of semiconductor device, or portion thereof, made from any of the various semiconductor processes, such as a complementary metal oxide semiconductor (CMOS) process, a bipolar process, or another semiconductor process. Portion **10** may be an entire IC or a portion of an IC, and may include a multitude of electronic component portions.

[0031] Portion **10** preferably includes CMOS transistors provided in at least one N-well or region **12** and at least one P-well or region **14**. N-well or region **12** is preferably comprised of silicon or strained silicon doped with N-type dopants. P-well or region **14** is preferably silicon or strained silicon doped with P-type dopants. N-type and P-type dopants are well known in the art.

[0032] Substrate **20** can be a P-type substrate such that P-well or region **14** is part of substrate **20** and is not a separate region in substrate **20** as shown in FIGURES 1 and 2. Alternatively, substrate **20**

can be an N-type substrate within which P-well or region **14** is provided. In such an embodiment, N-well or region **12** can be part of substrate **20** or can be provided within another P-well.

[0033] N-well or region **12** and P-well or region **14** are separated by trench structure **16**. As shown in FIGURE 1, trench structure **16** covers all four sides of N-well or region **14** and P-well or region **12**, however, other configurations for structure **16** can be utilized. Preferably, trench structure **16** extends beyond a bottom most part of N-well or region **12** and P-well or region **14**. Transistors having N-channel regions can be disposed in region **14** and transistors having P-channel regions can be disposed in region **12** in accordance with CMOS techniques. Regions **12** and **14** can contain various transistor structures such as source and drain regions, extensions, channel regions, etc.

[0034] With reference to FIGURE 3, trench structure **16** (encircled by curve 3 in FIGURE 2) includes trench fill material **19** disposed between a first liner **22** and a second liner **24**. Liner **22** is preferably optimized for stress associated with N-well or region **12** and liner **24** is preferably optimized for stress associated with P-well or region **14**. Liner **22** is provided on a side wall **17** of trench structure **16** associated with region **12** and liner **24** is provided on a side wall **19** of trench structure **16** associated with region **14**.

[0035] In one embodiment, trench structure **16** has a width from side wall **17** to side wall **16** of 1000-5000 angstroms and a depth of 300-3000 angstroms. Trench structure **16** can be a shallow trench isolation (STI) structure. Trench structure **16** including liners **22** and **24** can have a depth greater than regions **12** and **14**.

[0036] Liner **22** is optimized such that the stress in P-well

12 associated with or caused by liner **22** is similar to the stress in P-well **14** associated with or caused by liner **24**. In a first embodiment, the material of liner **22** is different than the material of liner **24** such that the stress in regions **12** and **14** is similar. In a second embodiment, the thickness of liner **22** is different than the thickness of liner **24** such that the stress in regions **12** and **14** is similar. In a third embodiment, the material and thickness of liner **22** and the material and thickness of liner **24** is different so that the stress in regions **12** and **14** is similar.

[0037] In one embodiment, liner **24** associated with P-well region **14** is a dry oxide material (pure oxide) and liner **22** associated with region **12** is a dry heavily nitrided oxide. Alternatively, liner **22** can be manufactured from a different material that causes tensile stress in region **12**. In one embodiment, liners **22** and **24** are different materials chosen from silicon oxides, nitrides, and oxynitrides. Liners **22** and **24** can have thicknesses of 50-400 Å and sufficiently densified to create stress. Generally, it is desirous to have P-well or region **14** with compressive stress associated with liner **24** and N-well or region **12** having tensile stress.

[0038] With reference to FIGURES 1-4, a process **100** can be utilized to form trench structure **16** (FIGURES 1-3). In a step **102**, an aperture or trench for trench structure **16** is etched in substrate **20**. The trench can be used to define wells or regions **12** and wells or regions **14** as well as active regions within regions **12** and **14**. Regions **12** and **14** can be formed before or after the aperture for trench structure **16** as formed. Preferably, a hard mask etching step is utilized to form the aperture for trench structure **16**. The etching step can be a dry etching step selective to the material of substrate **20**.

[0039] In a step 104 of process 100, a liner such as liner 22 is provided on a sidewall 17 associated with well or region 12. The liner is covered with a hard mask after forming. The mask does not cover side wall 21. In a step 106, liner 24 is provided on side wall 21. Liner 24 is manufactured from a different material than liner or has a different thickness or both a different material and thickness than liner 22. In a step 108, trench fill material 19 is provided between liners 22 and 24 to complete trench 16. Trench fill material 19 can be blanket deposited over substrate 20 and etched or planarized to leave material 19 within the aperture associated with trench 16. Trench fill material 19 is a TEOS material.

[0040] With reference to FIGURES 4-8, process 100 is described in more detail below as follows. In FIGURE 5, an aperture 26 for trench 16 is etched (step 102), leaving side wall 17 associated with region 12 and sidewall 21 associated with region 14. Aperture 26 is preferably etched to a depth below a bottom of region 12 or 14. Substrate 20 is selectively etched using a hard mask such as a silicon nitride layer 36 selectively patterned using photolithography according to step 102.

[0041] In FIGURE 6, a mask material, such as, a photoresist layer or hard mask layer is provided on sidewall 21 and above a top surface of layer 36 over region 14. In one embodiment, a layer of silicon nitride or silicon oxynitride is provided over sidewall 21 and layer 36 above region 14. Layer 38 can selectively coat sidewall 21 and not coat sidewall 17 through the use of photolithographic patterning techniques. Alternatively, a mask layer can be provided within aperture 26 and etched in at an angle to leave the mask layer on only sidewall 21.

[0042] After layer **38** is provided to protect sidewall **21**, layer or liner **22** is formed on sidewall **17** (step 104 of process 100). Liner **22** can be formed in a variety of processes. Preferably, liner **22** is formed by thermally growing a silicon dioxide material. In one embodiment, liner **32** is formed in a thermal process using a pure dry oxide ambient. Liner **22** can have a thickness of 50-400 Å.

[0043] In alternative embodiments, liner **22** can be formed in a low temperature process and be between approximately 200 and 500 Å thick. Liner **22** can also be formed on a bottom of aperture **16** associated with trench isolation structure **16**. Alternatively, the bottom of aperture **26** can also be covered by layer **38**.

[0044] In another embodiment, liner **22** is formed in an ultraviolet ozone (UVO) process. In such an embodiment, sidewall **17** is exposed to UV light to form ozone (O_3) and atomic oxygen (O) by absorbing UV light having a wavelength of approximately 185 nm. Once formed, the ozone can undergo further decomposition to form additional atomic oxygen by absorbing UV light having a wavelength of about 254 nm.

[0045] In another alternative, a PECVD process, such as dual frequency RF power PECVD process, can be utilized to form liner **22** at temperatures between 500 and 550°C. In yet another embodiment, liner **22** can be formed by an atomic layer deposition (ALD) technique having a temperature of approximately 700°C with a saline and oxygen atmosphere. In yet another embodiment, liner **32** can be formed in a high density oxide deposition (HDP) process, such as an HDP process utilizing RF power.

[0046] With reference to FIGURE 7, after liner **22** is

formed, material **38** is removed from sidewall **21**. Layer **38** can be removed in a dry etching process selective to material **38** such as a dry etching process selective to silicon nitride with respect to silicon dioxide and silicon. A mask layer or material **39** is provided above layer **36** associated with region **12** and over liner **22**. Layer or material **39** is preferably similar to material **38** and covers liner **22**.

[0047] After liner **22** is protected by material **39**, a liner **24** is grown on sidewall **21** (step **106**). Liner **24** is similar to liner **22**, however, liner **24** is grown in a process different than a process used to create liner **22** or is grown to a different thickness than liner **24**.

[0048] In a preferred embodiment, liner **22** is grown by a dry oxide process and liner **24** is grown by a dry nitrided oxide process. Liner **24** can be 50-400 Å thick. After liner **24** is formed, material **39** is removed. In one embodiment, material **36** can also be removed.

[0049] With reference to FIGURE 8, trench fill material **19** is provided between liners **22** and **24**. Material **19** is preferably silicon dioxide deposited in a high density plasma (HDP) process or in a tetraethylorthosilicate (TEOS) process. Alternatively, a boron phosphate silicon glass (BPSG) process can be used. Material **19** preferably fills aperture **26** with trench structure **16** and can be approximately 2,000-8,000 Å thick. Material **19** is removed by polishing/etching until a top surface of layer **36** or substrate **20** is reached.

[0050] With reference to FIGURES 1-4 and 9-13, process **100** is provided on a substrate **220** shown in FIGURE 9 as a silicon-on-insulator (SOI) substrate. Substrate **220** includes a base layer **229**, such as a single crystal silicon layer, and a silicon dioxide layer or buried oxide layer, such as layer **223**. A layer **225** is provided above layer **223**. Layer

225 is preferably a strained silicon layer. Layer **223** can provide appropriate seeding for a strained layer such as layer **225**.

[0051] Layer **225** can be formed above layer **223** in an epitaxial process, such as growth by CVD. Alternatively, layer **225** can be other deposition processes. Layer **16** can have a thickness between 50 and 150Å. Layer **225** can be similar to substrate **20** and can include germanium. Layer **225** can be formed by utilizing germanium or other methods for providing strained in layer **225**.

[0052] In FIGURE 9, portion **200** includes P-well or region **212** and N-well or region **214** similar to regions **12** and **14**, respectively. A shallow trench isolation structure **216** is provided in portion **200**. Structures in FIGURES 9-13 similar to structures in FIGURES 5-8 have reference numerals differentiated by **200**.

[0053] Liners **222** and **224** similar to liners **22** and **24** are provided between sidewalls **217** and **221**. Preferably, trench structure **216** extends from a top surface of layer **225** to a bottom surface of layer **225** or top surface of layer **223**.

[0054] Trench structure **216** preferably has a depth of between approximately 1500 and 4000 Å and a width of 0.18-1.50 nm or below. Trench structure **216** can have a trapezoidal cross-sectional shape with the narrower portion being at the bottom. Trench structure **16** can also have other cross-sectional shapes.

[0055] With reference to FIGURES 9-13, process **100** is described in more detail below as follows. In FIGURE 10, an aperture **226** for trench **216** is etched (step **102**), leaving sidewall **217** associated with region **212** and sidewall **221** associated with region **214**. Aperture **226** is

preferably etched to a depth below a bottom of region **212** or **214**. Substrate **220** is selectively etched using a hard mask such as a silicon nitride layer **236** selectively patterned using photolithography according to step **102**.

[0056] In FIGURE 11, a mask material, such as, a photoresist layer or hard mask layer **238** is provided on sidewall **221** and above a top surface of layer **236** over region **214**. In one embodiment, a layer of silicon nitride or silicon oxynitride is provided over sidewall **221** and layer **236** above region **214**. Layer **238** can selectively coat sidewall **221** and not coat sidewall **217** through the use of photolithographic patterning techniques. Alternatively, a mask layer can be provided within aperture **226** and etched in at an angle to leave the mask layer on only sidewall **221**.

[0057] After layer **238** is provided to protect sidewall **221**, layer or liner **222** is formed on sidewall **217** (step **104** of process **100**). Liner **222** can be formed in a variety of processes. Preferably, liner **222** is formed by thermally growing a silicon dioxide material. In one embodiment, liner **22** is formed in a thermal process in a pure dry oxide ambient. Liner **222** can have a thickness of 50-400 Å. In alternative embodiments, liner **222** can be formed in process similar to any of the processes used to form liner **22** (FIGURE 6).

[0058] With reference to FIGURE 12, after liner **222** is formed, material **238** is removed from sidewall **221**. Layer **238** can be removed in a dry etching process selective to material **238** such as a dry etching process selective to silicon nitride with respect to silicon dioxide and silicon. A mask layer **239** is provided above layer **236** associated with region **212** and liner **222**. Material layer **239** is preferably similar to

material **238** and covers liner **222**.

[0059] After liner **222** is protected by layer **239**, a liner **224** is grown on sidewall **221** (step **106**). Liner **224** is similar to liner **222**, however, liner **224** is grown in a process different than a process used to create liner **222** or has a different thickness than liner **222**. In a preferred embodiment, liner **222** is grown by a dry oxide process and liner **224** is grown by a dry nitride/oxide process. After liner **224** is formed, material **239** is removed. Liner **224** can be 50-400 Å thick. In one embodiment, material **236** can also be removed.

[0060] With reference to FIGURE 13, trench fill material **219** is provided between liners **222** and **224**. Material **219** is preferably silicon dioxide deposited in a high density plasma (HDP) process or tetraethylorthosilicate (TEOS) process. Alternatively, a boron phosphate silicon glass (BPSG) process can be used. Material **219** preferably fills aperture **226** with trench structure **216** and can be approximately 2,000-8,000 Å thick. Material **219** is removed by polishing/etching until a top surface of layer **236** or substrate **220** is reached.

[0061] It is understood that while the detailed drawings, specific examples, and particular values given provide a preferred exemplary embodiment of the present invention, it is for the purpose of illustration only. The shapes and sizes of trenches and liners are not disclosed in a limiting fashion. The method and apparatus of the invention is not limited to the precise details and conditions disclosed. Various changes may be made to the details disclosed without departing from the spirit of the invention, which is defined by the following claims.